Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: ***Networking***
Marketing Name / Model **[List multiple models if applicable.]**
HPE ANW ClearPass N300x HW Appliance

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.
1.3 Quantities vary by product configuration

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Quantity varies by product configuration and power supply model selected	3 to 8
External electrical cables and cords	Quantity depends on number of power supplies, networking devices, and I/O devices	1 to 8
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

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Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T-10
Torx Driver	T-15
Torx Driver	T-20
Hex socket	3/16
Screwdriver Cross Type	PH-0
Screwdriver Cross Type	PH-1
Screwdriver Flat type	4.0
Sharp Nose Pliers	
Soldering Iron	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disconnect all cables
2. Remove System Fans and PCIE Fan
3. Remove RPSU
4. Remove PCIE Riser Cage and PCIE adaptor
5. Remove OCP module
6. Remove Air baffle
7. Remove CPU Heatsink and CPU
8. Remove Megacell Battery Holder
9. Remove DIMM Guard and PCIE holder bracket
10. Remove RTC battery
11. Remove Main Board
12. Remove the OCP rail
13. Remove Front bezel
14. Remove Latch Ear and Front Panel
15. Remove 4LFF Backplane
16. Remove 10SFF Backplane
17. Remove 2SFF Backplane
18. Remove ODD
19. Dissemble 500W PSU (Lite on)
20. Dissemble 1600W PSU
21. Dissemble 1000w PSU
22. Dissemble 800w PSU
23. Dissemble 1800w PSU

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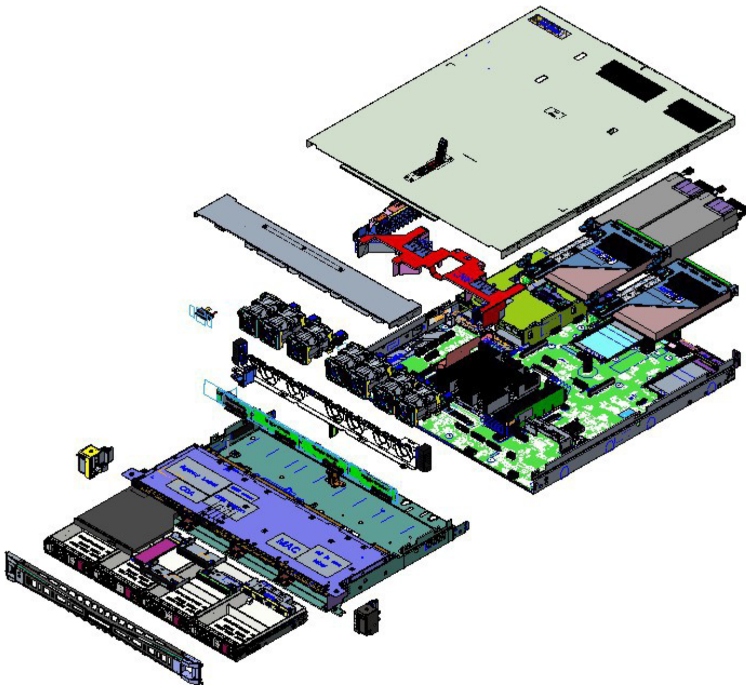
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1 – System exploding drawing



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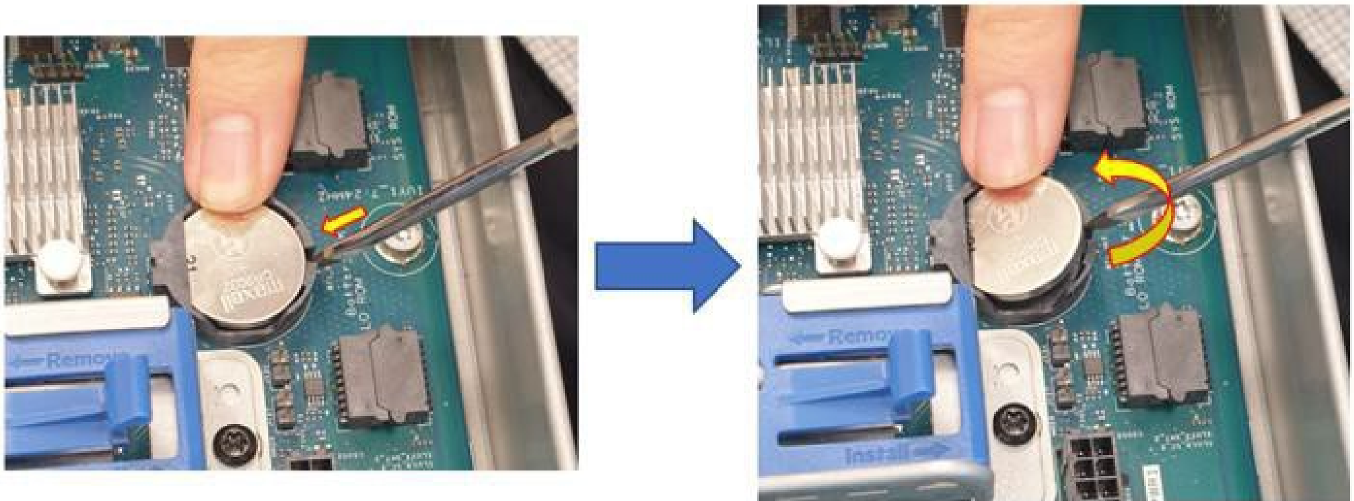
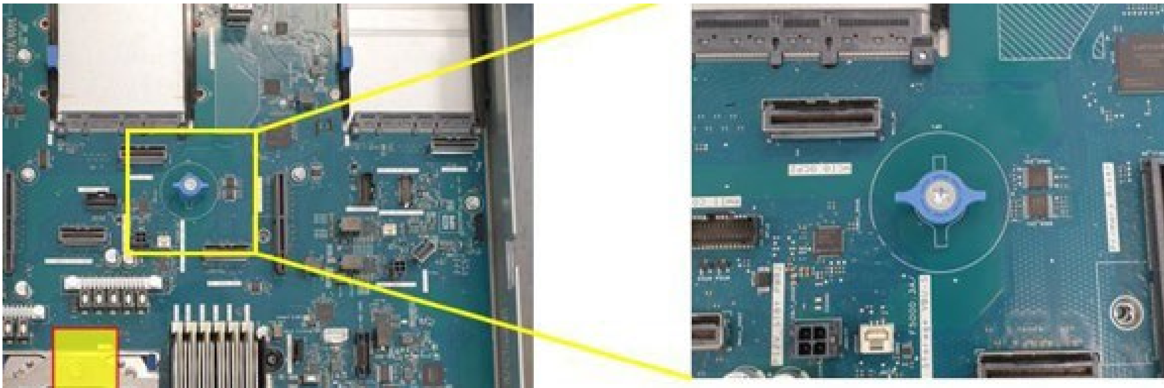
Attachment 2 - Remove RTC battery



Attachment 3- Remove MB

1. Loose the thumb screw to release MB from chassis



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Attachment 4 - Remove MB Rail

1. Use PH-1 screwdriver to remove the OCP MB rail

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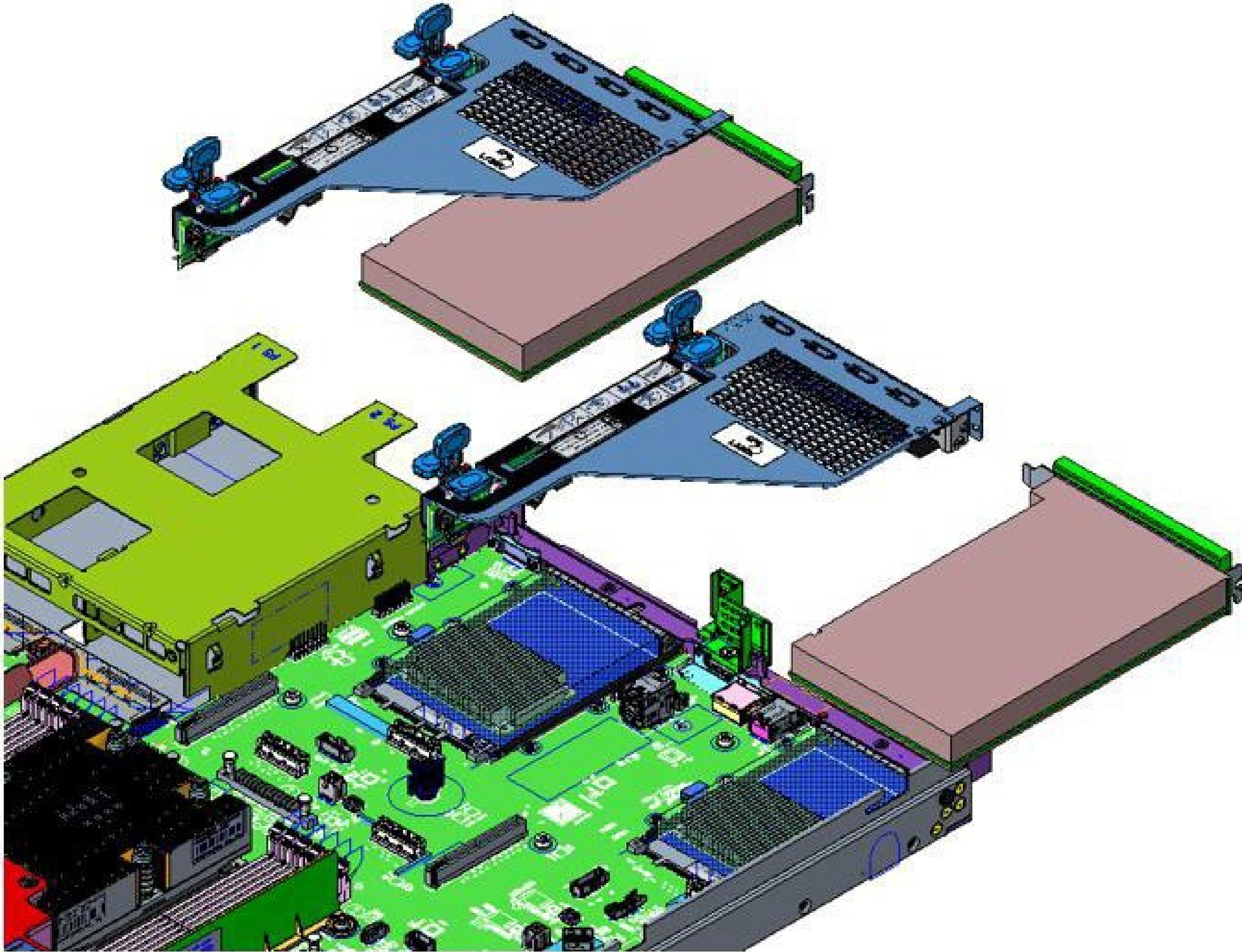
Attachment 5 - Remove PCIE Riser Cage and PCIE riser card

1. Release the half-turn spring latch
2. Lift the riser cage off the system board
3. Use T-10 screwdriver to release 1 screw to remove the PCIE card.
4. Use T-15 screwdriver to release 2 screws to remove PCIE riser from PCIE cage



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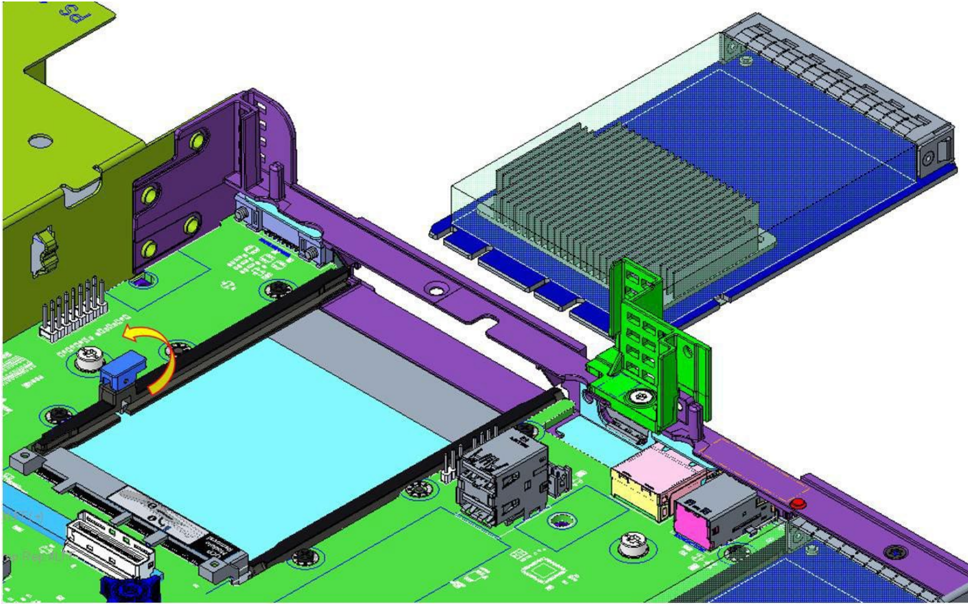
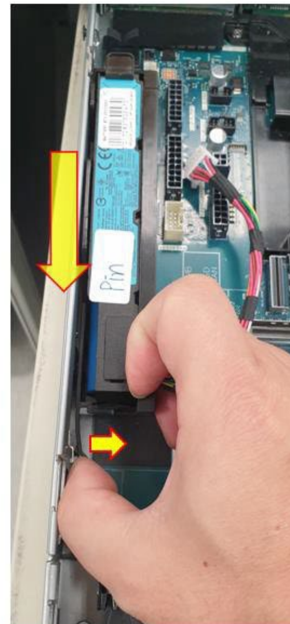
Attachment 6 - Remove OCP Module

1. Release the OCP MB rail lock latch
2. Remove the OCP card



Attachment 7 - Remove Megacell Module and Battery Holder

1. Use T-15 screwdriver to remove megacell battery holder



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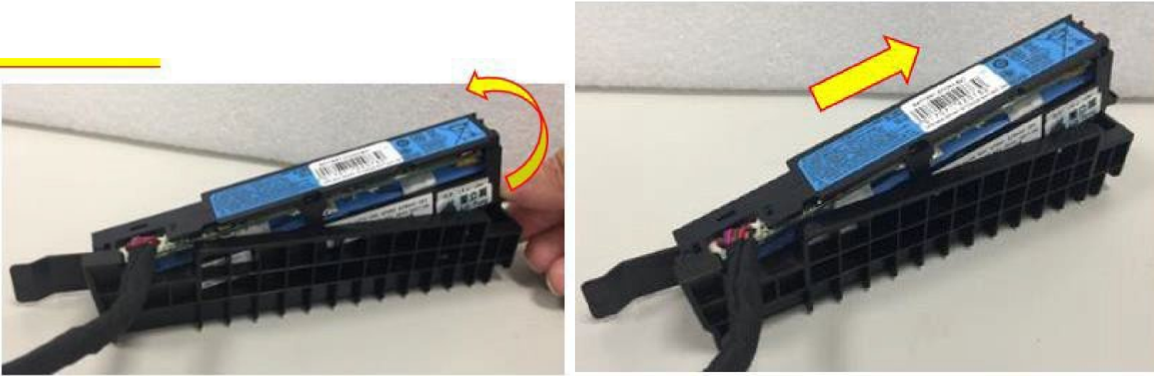
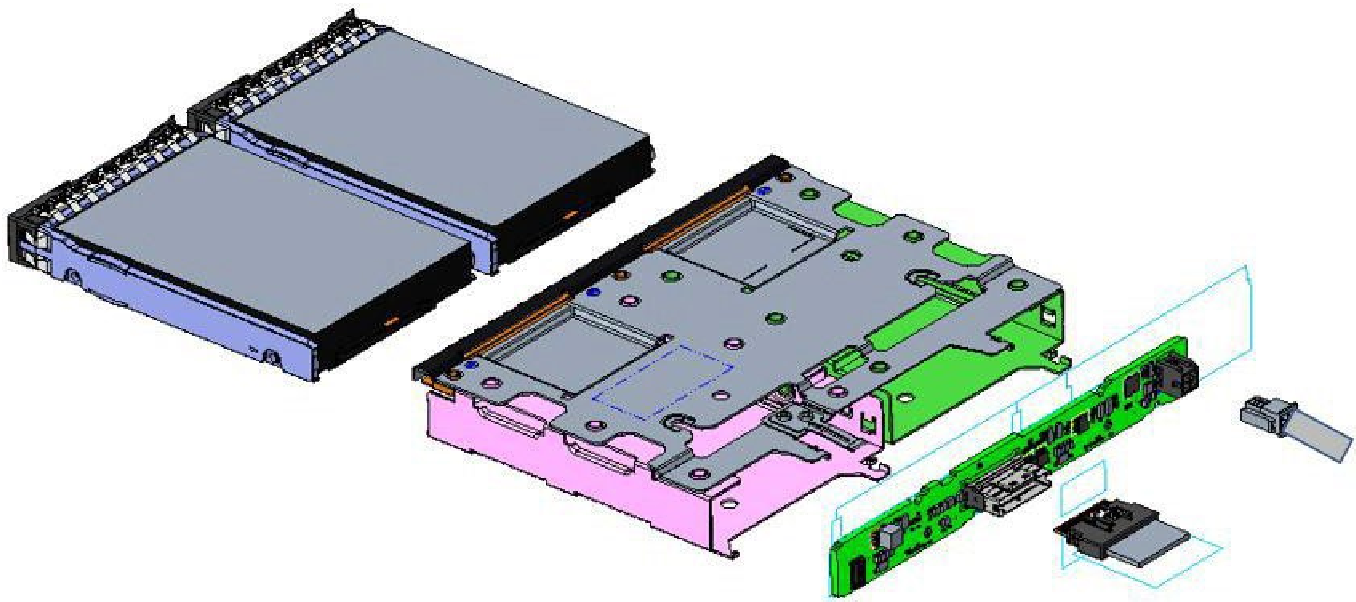


Attachment 8 – Remove Back Plane

1. Remove HDD and BP board from the 2SFF cage(2SFF)



Attachment 9 - Remove BP board

1. Remove BP single and power cable. (4LFF)

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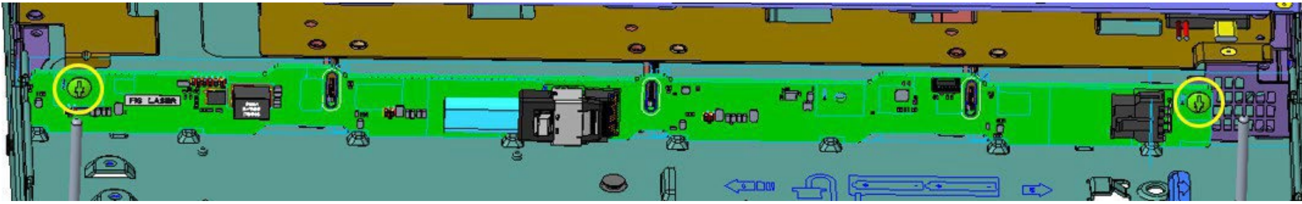
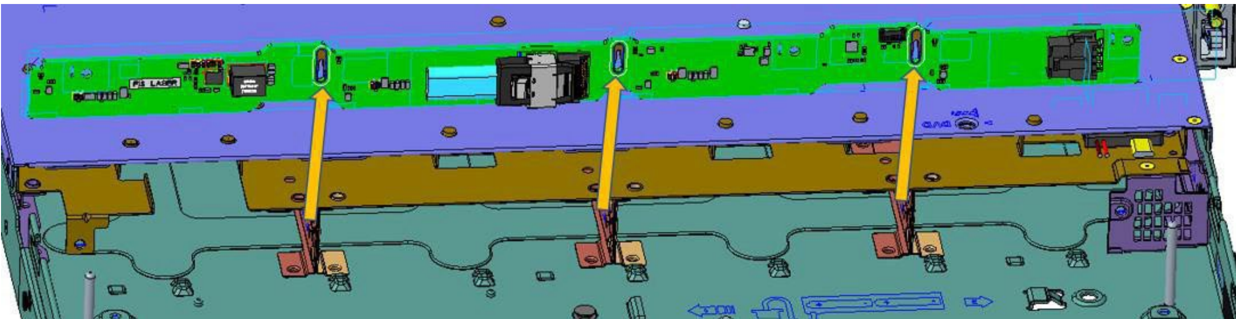
2. Use T-15 screwdriver to remove 2 screws. (4LFF)

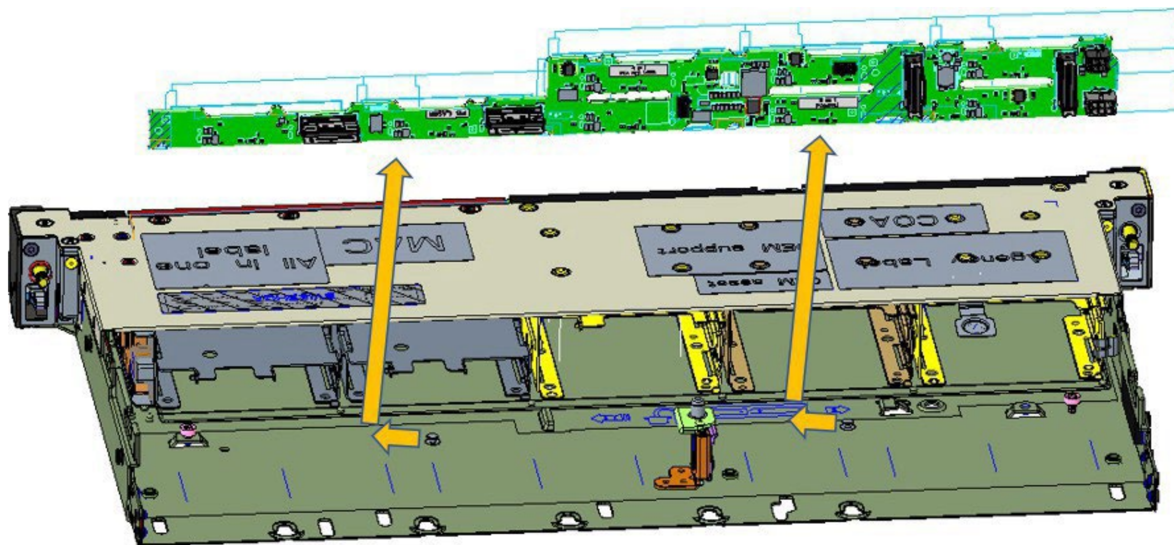


3. Slide the BP board to remove. (4LFF)



4. Remove BP single and power cable. (8SFF)

5. Slide the BP board to remove. (8SFF)



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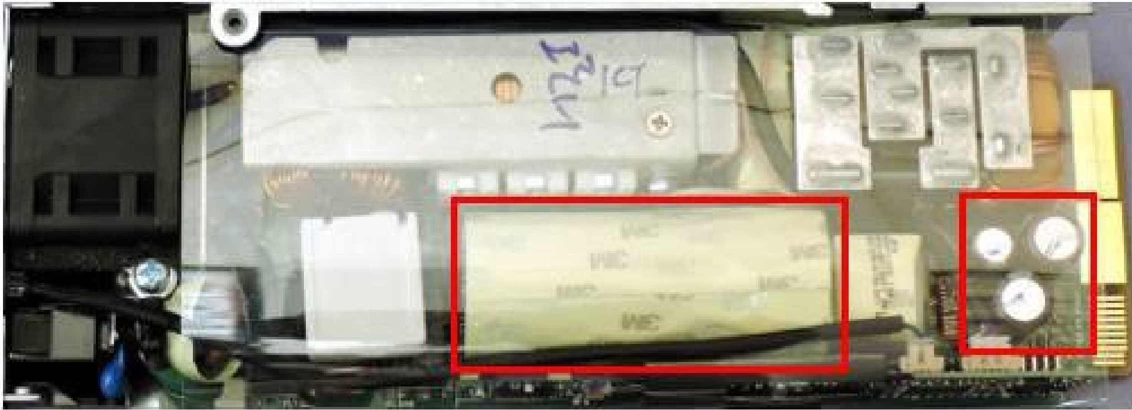
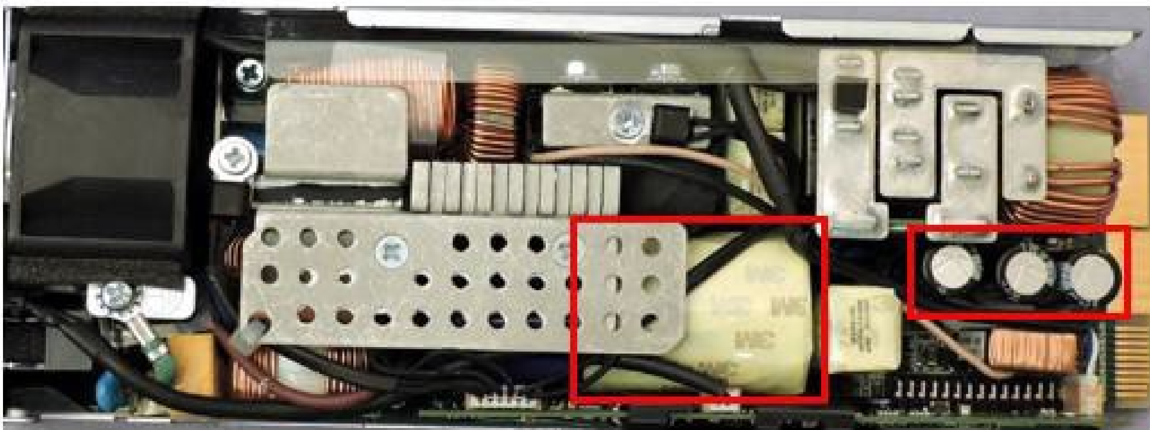
Attachment 10 – Remove Electrolytic Capacitors in PSU

1. HSTNS-PD41-1



2. HSTNS-PL41-1

3. HSTNS-PC41-1



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